

StarJet Technology: 3D Interconnections & Micro Assembly

StarJet Technology:

- Non-contact molten metal printing technology
- Direct printing molten metal at high reservoir temperature, e.g. solder SAC305 (320 °C) and Al alloy (950 °C)
- Low cost of material (i.e. bulk material used)
- Advantages:
 - High direction stability (printing distance up to 30 mm)
 - Operation under ambient condition (oxidation protection via inert sheath flow)
 - Tunable droplets / jet diameters via nozzle orifice modification (e.g. 70 µm – 300 µm)

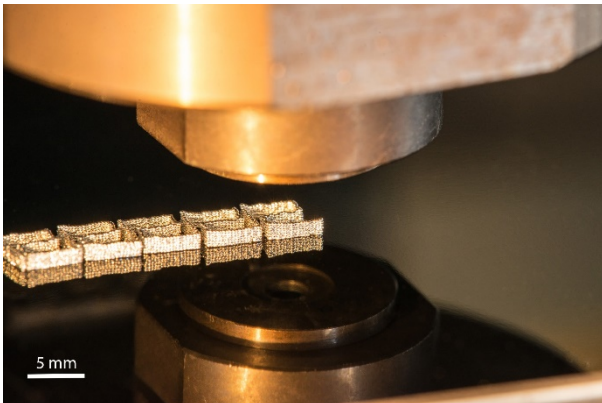
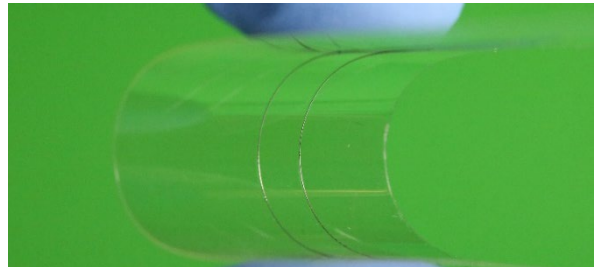


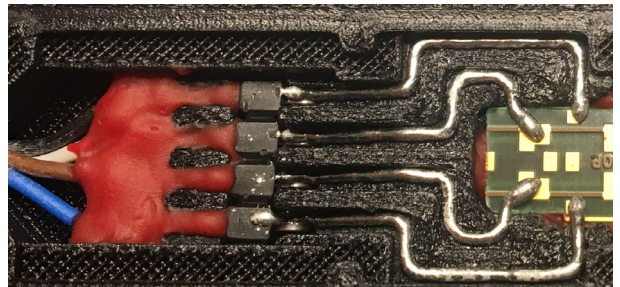
Photo of StarJet printhead with printed 3D metal structure on Si-wafer

Application case: flexible interconnections

- Non-contact printing of interconnections on flexible substrates, e.g. polymer, textiles
- High printed line aspect ratio (close to 1)
- Low electrical resistance
- High adhesion and flexibility
- Compatible to temperature sensitive substrates



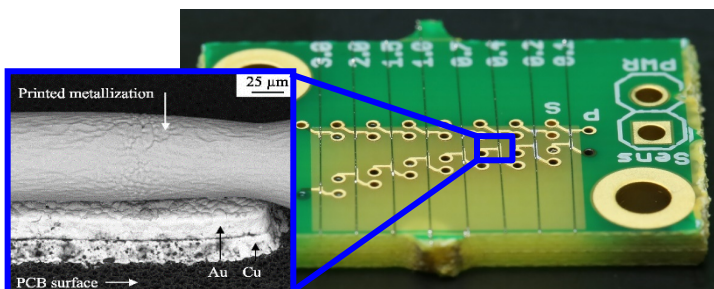
Metallization for flexible electronics: printed solder lines on a bent PET foil



Interconnecting PCBs and cable connectors through 3D printed housing

Application case: PCB interconnecting (2D & 3D)

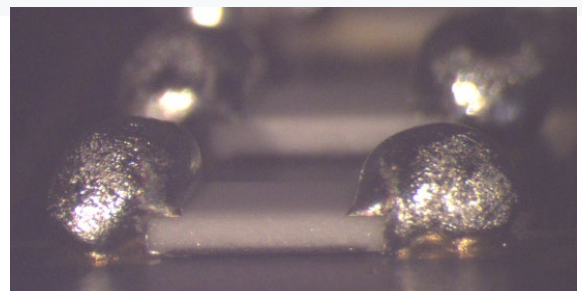
- Non-contact printing of interconnections on PCBs
- High printed line aspect ratio (close to 1)
- Low electrical resistance (4 µΩ/mm) for 10 mil lines
- Comparable adhesion to standard solder joint
- **Vertical interconnection printing (Via filling)**



Direct printing of interconnections on printed circuit boards (PCB)

Application case: Soldering of electronics

- Non-contact soldering of electronic components on various substrates (e.g. ENIG contact pads)
- Adhesion strength close to standard solder joints
- Low contact resistance
- **Localized soldering on temperature sensitive substrate**



Direct soldering of SMD resistors (size 1206)